

Multilayer Power Inductor

CIG32W Series (3225/ EIA 1210)

APPLICATION

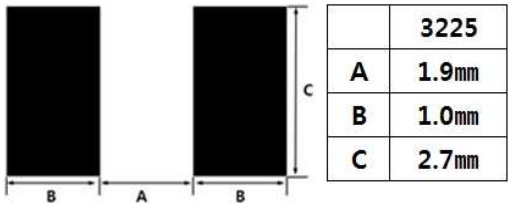
Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

FEATURES

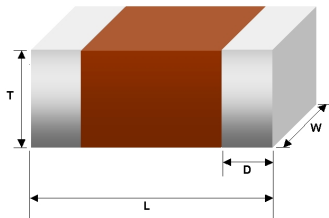
- High Current Type
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability



RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
32	3.2±0.2	2.5±0.2	0.9±0.1	0.5±0.3

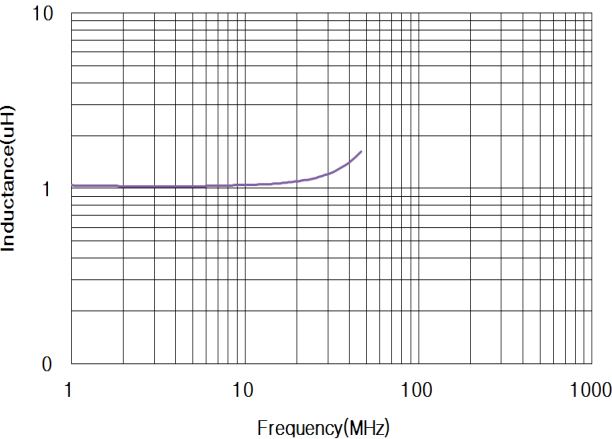
DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) ^{*1} Typ.	Rated Current (A) ^{*2}	
					Max.	Typ.
CIG32W1R0MNE	1210/3225	1.0±20%	0.06±25 %	2.7	1.5	2.0

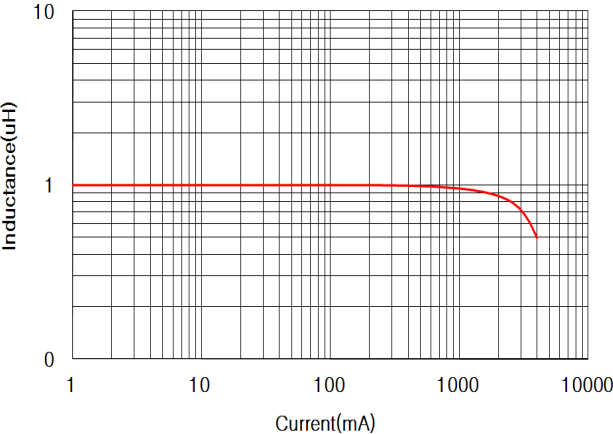
※Rated Current (A)^{*1}: DC current value when Inductance drops to 30% of nominal Inductance value (ONLY REFERENCE)
 ※Rated Current (A)^{*2}: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)
 ※Operating temperature range: -40 to +125℃ (Including self-temperature rise)
 ※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



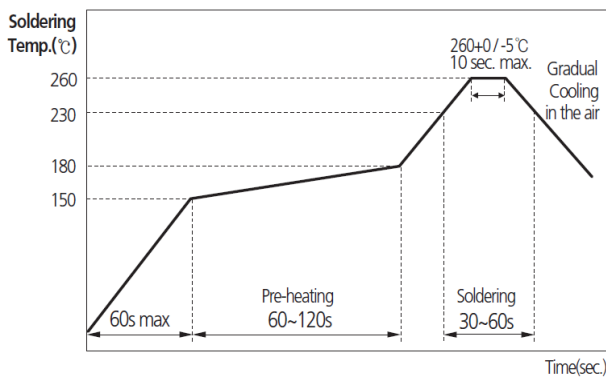
PRODUCT IDENTIFICATION

CI	G	32	W	1R0	M	N	E
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)

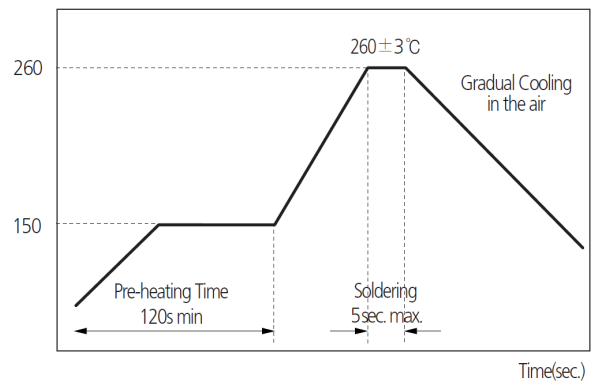
- | | |
|--|------------------------------------|
| (1) Chip Inductor | (2) Power Inductor |
| (3) Dimension | (4) Product Series (W:Normal Type) |
| (5) Inductance (1R0:1.0uH) | (6) Tolerance (M:±20%) |
| (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard) | |
| (8) Packaging(C:paper tape, E:embossed tape) | |

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	2,500



Any data in this sheet are subject to change, modify or discontinue without notice.

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.